# LNJ998CKBDA

### Round Type

 $\phi 3.0 \ mm$ 

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	120	mW	
Forward current	I <sub>F</sub>	30	mA	
Pulse forward current *	I <sub>FP</sub>	100	mA	
Reverse voltage	V <sub>R</sub>	5	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-30 to +100	°C	

Lighting Color

• Blue

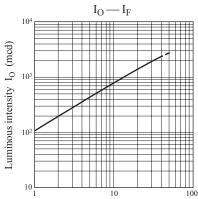
Note) \*: The condition of  $I_{\rm FP}$  is duty 10%, Pulse width 10 msec.

#### Electro-Optical Characteristics $T_a = 25^{\circ}C$

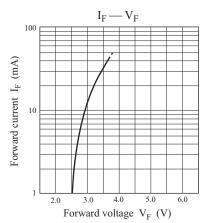
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I <sub>O</sub>	$I_{\rm F} = 20  {\rm mA}$	600	1 500		mcd
Reverse current	I <sub>R</sub>	$V_R = 5 V$			10	μΑ
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 20 \ {\rm mA}$		3.2	4.0	V
Dominant emission wavelength *2	$\lambda_d$	$I_F = 20 \text{ mA}$	457.5	459.0	460.0	nm

Note) \*1: Measurement tolerance:  $\pm 20\%$ 

\*2: Measurement tolerance:  $\pm 2 \text{ nm}$ 







Directive characteristics

20

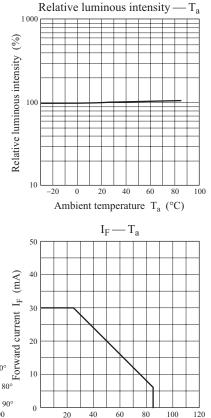
100 00

-60

-80

-90°

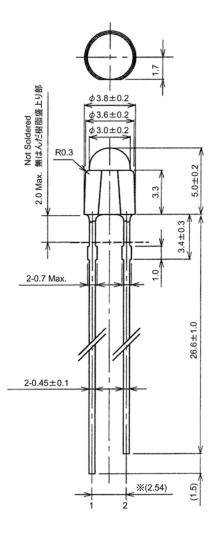
100 80 60 40 20 0 20 40 60 80 100

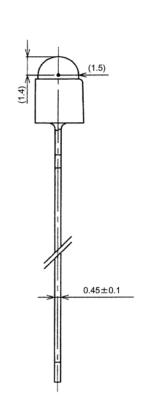


Ambient temperature  $T_a$  (°C)

Relative luminous intensity (%)

#### Package (Unit: mm)





• Pin name

1: Anode

2: Cathode

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